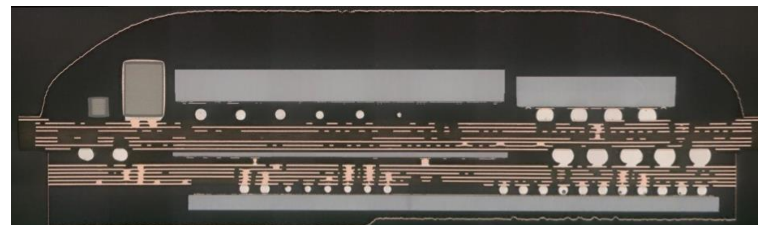


***Source*:**
Highly Integrated 3D-SiP:
Apple AirPods Pro,
Cross-Section by System
Plus Consulting 2019

Overview ESPAT-Consulting

European Semiconductor
Packaging, Assembly and Test

MAY/20, 2022

Dresden, Germany

Introduction ESPAT-Consulting

European Semiconductor Packaging, Assembly and Test (ESPAT) Consultancy Services Offer:

- **Packaging Technology** decision-making for new applications/products (Start-ups, SME);
- **Package Design**, Bill of Material (BOM) and Process of Record (POR) support;
- **Supply Chain** setup for prototypes, samples, small-medium-high volume manufacturing;
- **Technology Promotion** for innovative SPAT technology development companies;
- **Strategic Guidance** provision to SPAT equipment and material suppliers on what's next;
- **Technology Trend** analysis for Market Studies and Technology Reports;
- **Market Researchers** and Trend Scouting support;
- **Research Institutes** cooperation on national and European project acquisition;
- **Active Representation** of European SPAT in relevant international industry associations:
  - SEMI Europe - APC Chair @ SEMICON Europa, Founder & Vice Chair of ESiPAT-TC;
  - IEEE Electronics Packaging Society (EPS) - Elected to BoG 2021-2023 for Region 8 (EMEA);
  - IMAPS (Europe, US) - Conference Program Committee Member, and SMTA.

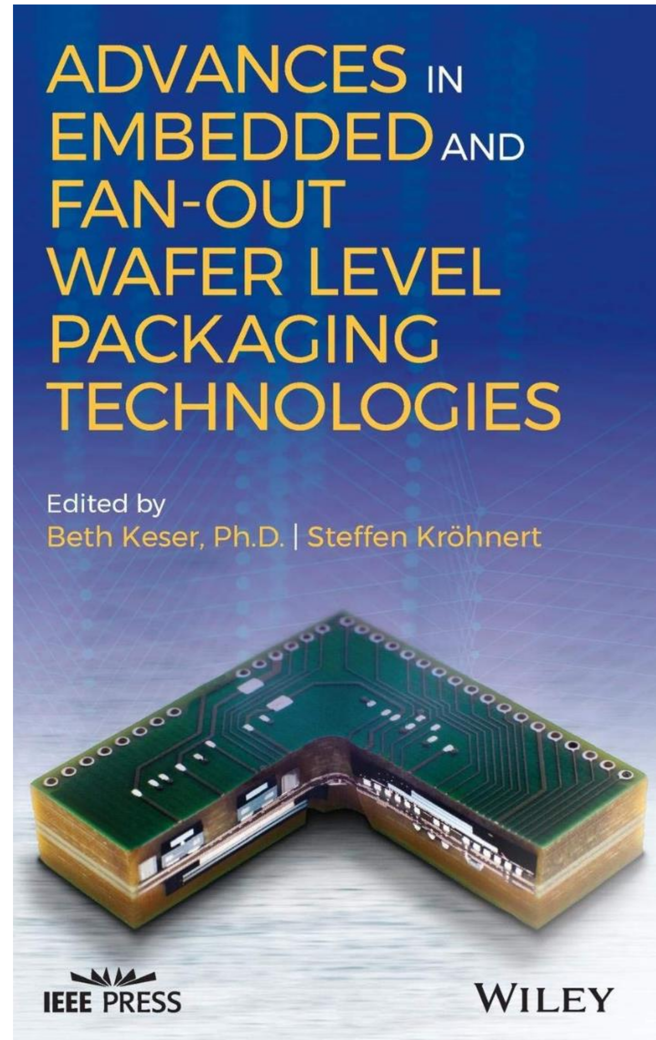
Background Steffen Kröhnert

TSOP → FBGA → AdvPkg/SiP/HI/WLP/FOWLP →

Chemnitz Hatfield (UK) Reutlingen Regensburg Dresden Porto Dresden/Porto Dresden - LOCATION -

1991 1997 1999 2002 2006 2010 2012 2017 2018 2019 2020+ - YEAR -

Recommended Reading by the Co-Editor



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Stay tuned for more to come in 2023/2024

Thanks for your attention !